

SN54AC573, SN74AC573 OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS

SCAS542D - OCTOBER 1995 – REVISED OCTOBER 2003

- 2-V to 6-V V_{CC} Operation
- Inputs Accept Voltages to 6 V
- Max t_{pd} of 9 ns at 5 V
- 3-State Outputs Drive Bus Lines Directly

description/ordering information

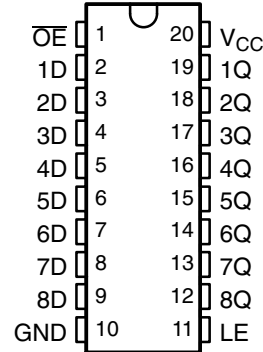
These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches are D-type transparent latches. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D Inputs.

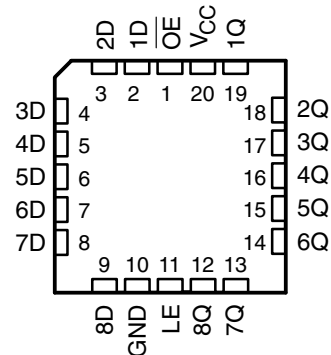
A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines in a bus-organized system without need for interface or pullup components.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

SN54AC573 . . . J OR W PACKAGE
SN74AC573 . . . DB, DW, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AC573 . . . FK PACKAGE
(TOP VIEW)



ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AC573N	SN74AC573N
	SOIC – DW	Tube	SN74AC573DW	AC573
		Tape and reel	SN74AC573DWR	
	SOP – NS	Tape and reel	SN74AC573NSR	AC573
	SSOP – DB	Tape and reel	SN74AC573DBR	AC573
	TSSOP – PW	Tube	SN74AC573PW	AC573
Tape and reel		SN74AC573PWR		
–55°C to 125°C	CDIP – J	Tube	SNJ54AC573J	SNJ54AC573J
	CFP – W	Tube	SNJ54AC573W	SNJ54AC573W
	LCCC – FK	Tube	SNJ54AC573FK	SNJ54AC573FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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**TEXAS
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To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

INPUTS			OUTPUT Q
OE	LE	D	
L	H	H	H
L	H	L	L
L	L	X	Q ₀
H	X	X	Z

[illegible]

Supply voltage range, V_{CC}		-0.5 V to + 7 V
Input voltage range, V_I (see Note 1)		-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)		-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)		± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)		± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		± 50 mA
Continuous current through, V_{CC} or GND		± 200 mA
Package thermal impedance, θ_{JA} (see Note 2):		
	DB package	70°C/W
	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
	PW package	83°C/W
Storage temperature range, T_{sta}		-65°C to 150°C

NOTES:

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

SN54AC573, SN74AC573 OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS

SCAS542D - OCTOBER 1995 – REVISED OCTOBER 2003

recommended operating conditions (see Note 3)

			SN54AC573		SN74AC573		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	$V_{CC} = 3\text{ V}$	2.1		2.1		V
		$V_{CC} = 4.5\text{ V}$	3.15		3.15		
		$V_{CC} = 5.5\text{ V}$	3.85		3.85		
V_{IL}	Low-level input voltage	$V_{CC} = 3\text{ V}$		0.9		0.9	V
		$V_{CC} = 4.5\text{ V}$		1.35		1.35	
		$V_{CC} = 5.5\text{ V}$		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 3\text{ V}$		-12		-12	mA
		$V_{CC} = 4.5\text{ V}$		-24		-24	
		$V_{CC} = 5.5\text{ V}$		-24		-24	
I_{OL}	Low-level output current	$V_{CC} = 3\text{ V}$		12		12	mA
		$V_{CC} = 4.5\text{ V}$		24		24	
		$V_{CC} = 5.5\text{ V}$		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			8		8	ns/V
T_A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25^\circ\text{C}$			SN54AC573		SN74AC573		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	$I_{OH} = -50\text{ }\mu\text{A}$	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	$I_{OH} = -12\text{ mA}$	3 V	2.58			2.48		2.48		
		4.5 V	3.94			3.8		3.8		
	$I_{OH} = -24\text{ mA}$	5.5 V	4.94			4.8		4.8		
	$I_{OH} = -75\text{ mA}^\dagger$	5.5 V				3.85		3.85		
V_{OL}	$I_{OL} = 50\text{ }\mu\text{A}$	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	$I_{OL} = 12\text{ mA}$	3 V			0.36		0.44		0.44	
		4.5 V			0.36		0.44		0.44	
	$I_{OL} = 24\text{ mA}$	5.5 V			0.36		0.44		0.44	
	$I_{OL} = 75\text{ mA}$	5.5 V				1.65		1.65		
I_I	$V_I = V_{CC}$ or GND	5.5 V			± 0.1		± 1		± 1	μA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			± 0.25		± 5		± 2.5	μA
I_{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		80		40	μA
C_i	$V_I = V_{CC}$ or GND	5 V			5					pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

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SN54AC573, SN74AC573

OCTAL D-TYPE TRANSPARENT LATCHES

WITH 3-STATE OUTPUTS

SCAS542D - OCTOBER 1995 – REVISED OCTOBER 2003

timing requirements over recommended operating free-air temperature range, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see Figure 1)

		$T_A = 25^\circ\text{C}$		SN54AC573		SN74AC573		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	6		8		7		ns
t_{su}	Setup time, data before LE↓	3.5		5		4		ns
t_h	Hold time, data after LE↓	2		3		2		ns

timing requirements over recommended operating free-air temperature range, $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$ (unless otherwise noted) (see Figure 1)

		$T_A = 25^\circ\text{C}$		SN54AC573		SN74AC573		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, LE high	4		6		5		ns
t_{su}	Setup time, data before LE↓	3		4.5		3.5		ns
t_h	Hold time, data after LE↓	2		3		2		ns

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$		SN54AC573		SN74AC573		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	2.5	13	1.5	16.5	2	15	ns
t_{PHL}			2.5	12	1.5	15.5	2	14	
t_{PLH}	LE	Q	2.5	13	1.5	16.5	2	15	ns
t_{PHL}			2.5	12	1.5	15.5	2	14	
t_{PZH}	OE	Q	2.5	11	1.5	13.5	2	12	ns
t_{PZL}			2.5	11	1.5	14	2	12.5	
t_{PHZ}	$\overline{\text{OE}}$	Q	2.5	12.5	1.5	15	2	13.5	ns
t_{PLZ}			2.5	9.5	1.5	12	2	10.5	

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$		SN54AC573		SN74AC573		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	2.5	10	1.5	13	2	11.5	ns
t_{PHL}			2.5	9.5	1.5	12.5	2	11	
t_{PLH}	LE	Q	2.5	9.5	1.5	12.5	2	11	ns
t_{PHL}			2.5	8.5	1.5	11.5	2	10	
t_{PZH}	$\overline{\text{OE}}$	Q	2.5	9	1.5	11.5	2	10	ns
t_{PZL}			2.5	8.5	1.5	11	2	9.5	
t_{PHZ}	$\overline{\text{OE}}$	Q	2.5	11	1.5	13.5	2	12	ns
t_{PLZ}			2.5	8	1.5	10.5	2	9	

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50 \text{ pF}$	$f = 1 \text{ MHz}$	25	pF

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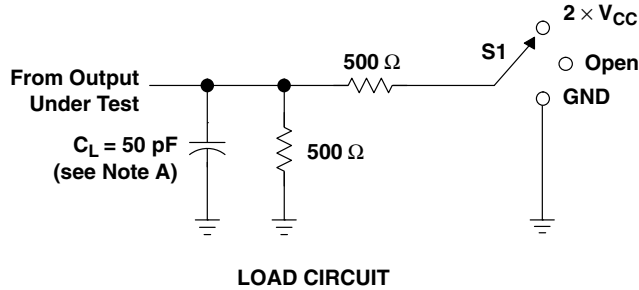


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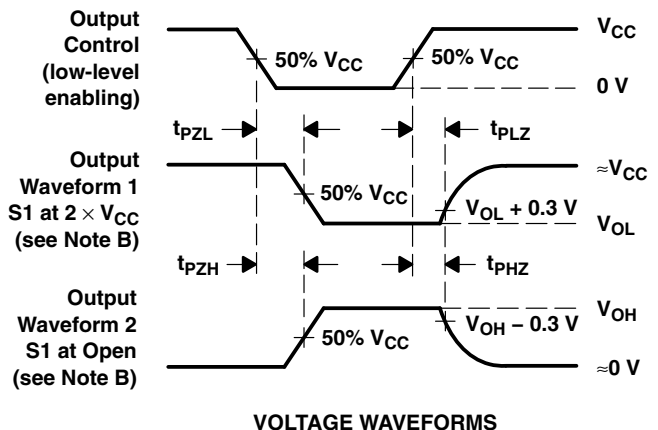
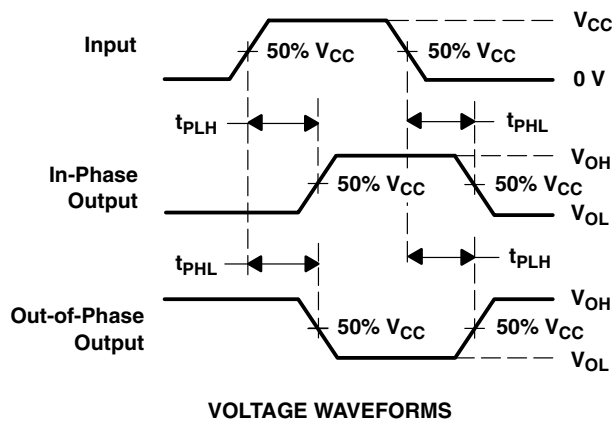
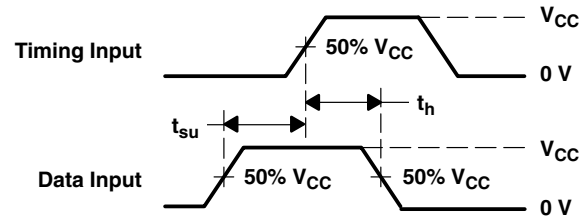
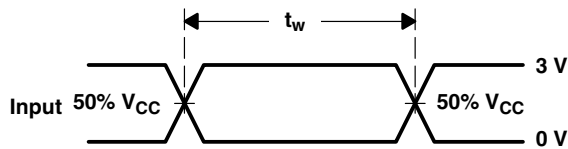
SN54AC573, SN74AC573 OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS

SCAS542D - OCTOBER 1995 - REVISED OCTOBER 2003

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	Open



NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.

D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AC573DBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC573	Samples
SN74AC573DBRG4	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC573	Samples
SN74AC573DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC573	Samples
SN74AC573DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC573	Samples
SN74AC573DWRG4	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC573	Samples
SN74AC573N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC573N	Samples
SN74AC573NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC573	Samples
SN74AC573PW	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC573	Samples
SN74AC573PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC573	Samples
SN74AC573PWRE4	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC573	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC573DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AC573DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74AC573NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74AC573PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC573DBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74AC573DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AC573NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AC573PWR	TSSOP	PW	20	2000	356.0	356.0	35.0

TUBE



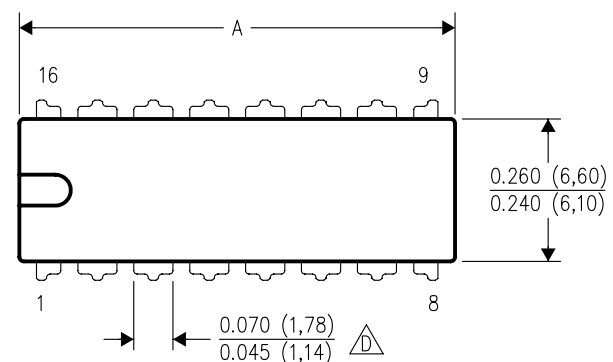
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74AC573DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74AC573N	N	PDIP	20	20	506	13.97	11230	4.32
SN74AC573PW	PW	TSSOP	20	70	530	10.2	3600	3.5

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE

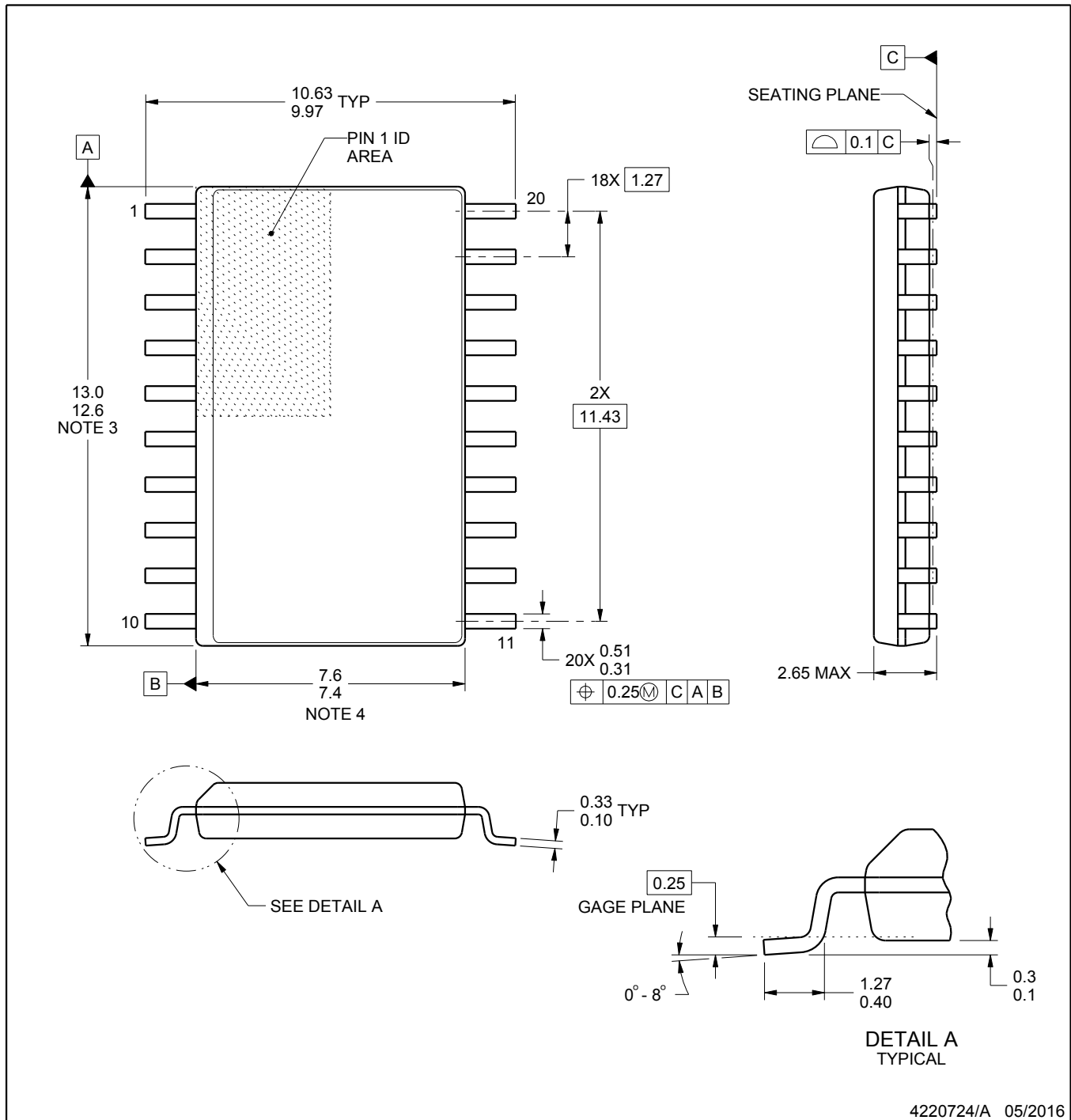
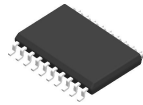


PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.



NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

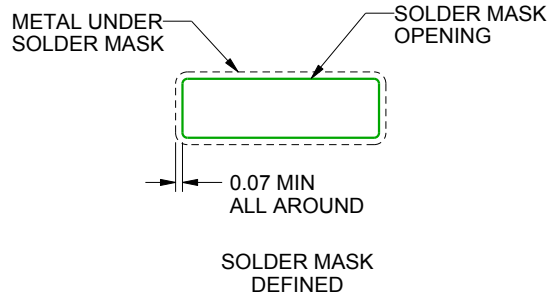
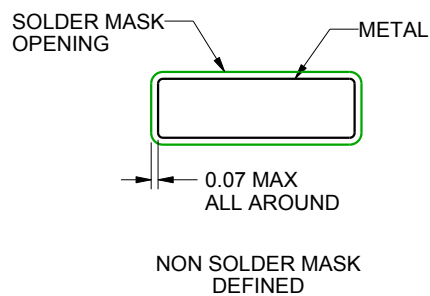
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC

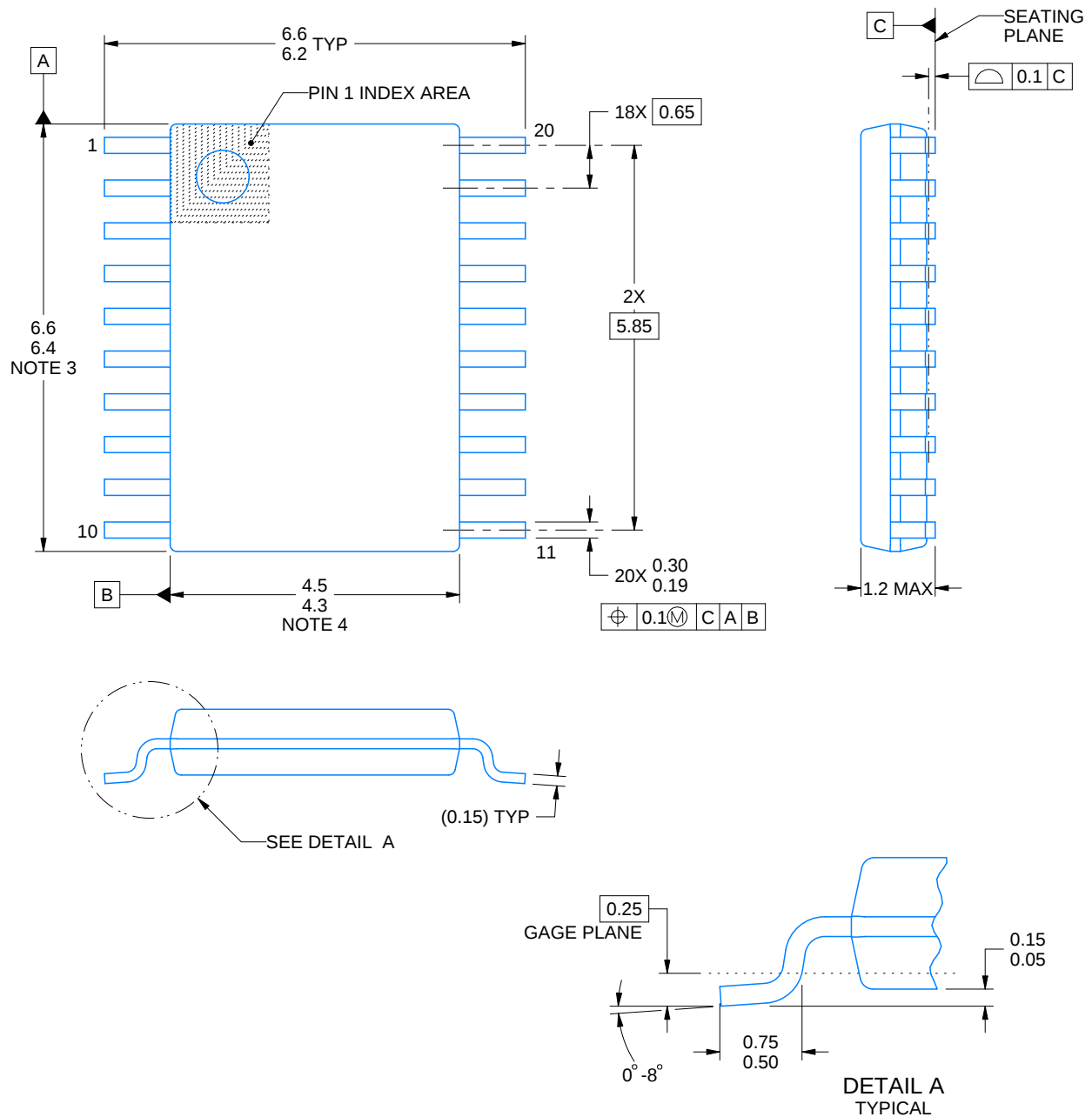
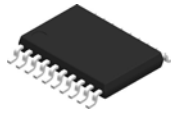


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4220206/A 02/2017

NOTES:

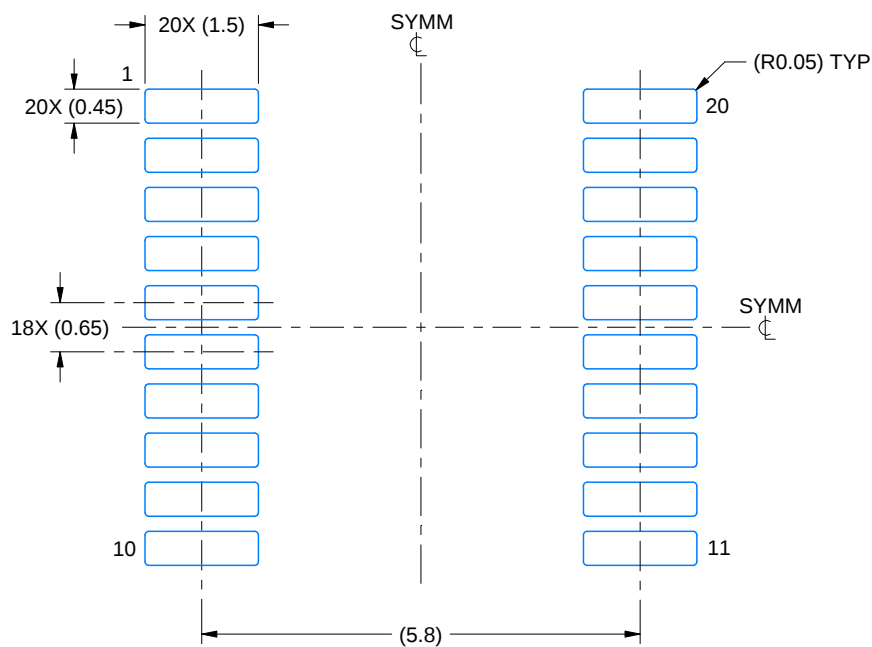
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

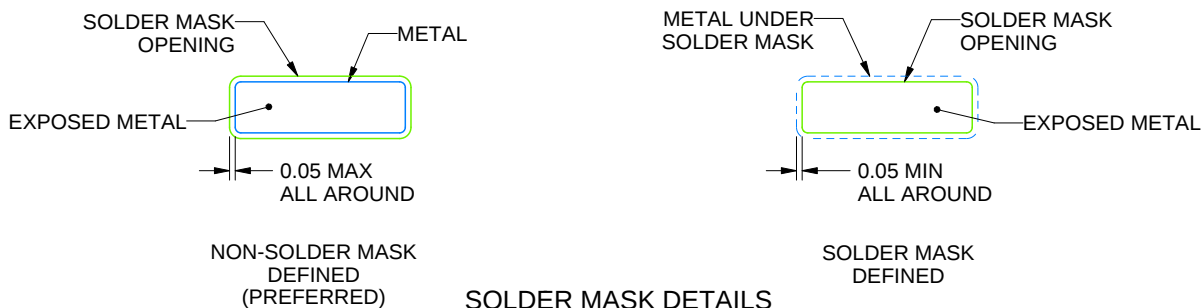
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

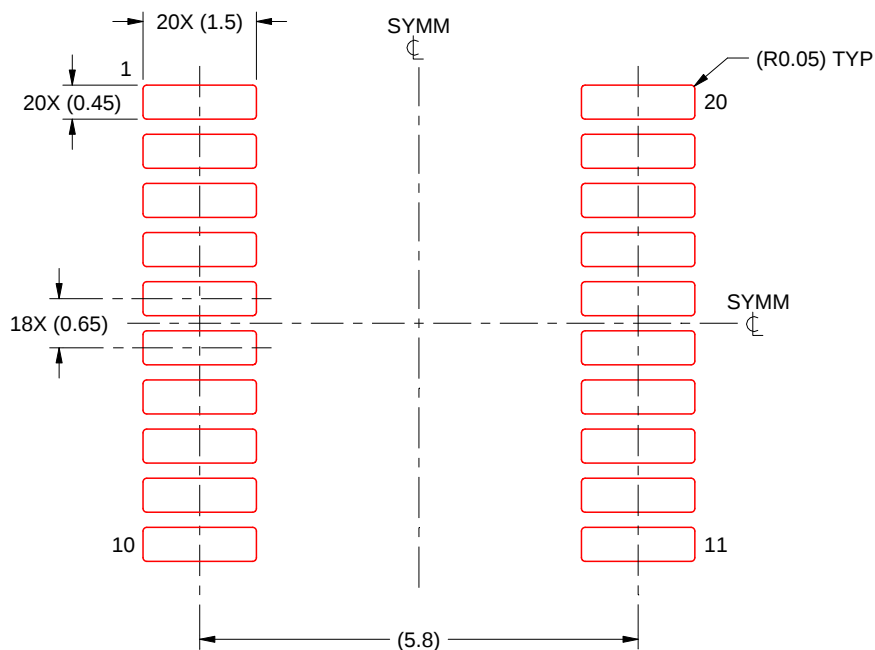
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

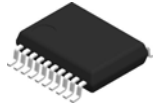
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



4214851/B 08/2019

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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